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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF :  
TOMOHISA KONNO ET AL : EXAMINER: RACHUBA, MAURINA T.  
SERIAL NO.: 10/626,521 :  
FILED: JULY 25, 2003 : GROUP ART UNIT: 3723  
FOR: AQUEOUS DISPERSION FOR :  
CHEMICAL MECHANICAL POLISHING  
AND PRODUCTION PROCESS OF  
SEMICONDUCTOR DEVICE

REQUEST FOR RECONSIDERATION

COMMISSIONER FOR PATENTS  
ALEXANDRIA, VIRGINIA 22313

SIR:

In response to the Office Action dated February 13, 2008, reconsideration and allowance are respectfully requested in view of the following remarks.

Claims 1-11, 13-15 and 18-21 are pending, claims 1-6, 8, 10 and 11 having been withdrawn from consideration.

Rejection Under 35 U.S.C. §103

The Office Action rejects claims 7, 9, 13-15 and 18-21 under 35 U.S.C. §103(a) over U.S. Patent No. 7,087,530 to Motonari et al. ("Motonari"). Applicants respectfully traverse the rejection.

Claim 7 recites "[a] process for producing a semiconductor device, comprising:  
polishing a surface of a semiconductor material with an aqueous dispersion for chemical  
mechanical polishing comprising abrasive grains and a heterocyclic compound; wherein: the